

Storage and Process Instructions:

For parts exposed to greater than 60% RH, it is recommended parts be baked at 125°C for 3-5 hours prior to SMT reflow process. If unsure of RH exposure, it is recommend to bake at the above temperature and time prior to SMT reflow process.

SPECIFICATIONS:

ELECTRICAL:
 RATED CURRENT: 5A
 RATED VOLTAGE: 300VDC
 WITHSTANDING VOLTAGE: 500VAC (rms) FOR 1 MIN
 INSULATION RESISTANCE: > 1,000 mΩ at 500VDC
 CONTACT RESISTANCE: 13mOhms MAX
 DIELECTRIC STRENGTH: 1000VAC FOR 1 MIN
 OPERATING TEMPERATURE: -55°C TO +105°C

MATERIALS:
 SHELL: NICKEL PLATED STEEL
 BRACKET: NICKEL PLATED STEEL
 INSULATOR: NYLON 6T, UL 94V-0, BLACK
 PROCESS TEMP: 260°C
 INSULATOR: PATONE #322C, COLOR=Pc99
 CONTACT: TIN PLATED PHOSPHOR BRONZE
 GOLD FLASH MATING AREA
 TIN PLATED SOLDER AREA

RoHS COMPLIANT

UNITS = inch [mm]

DO NOT SCALE FROM DRAWING



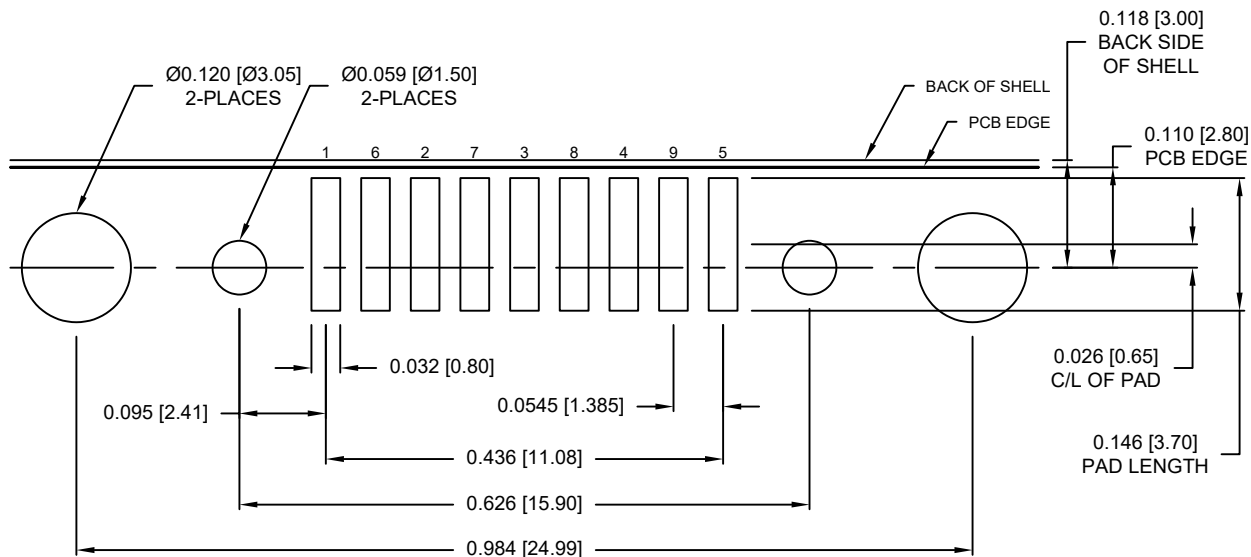
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DRAWN:
 C. SMITH

DATE:
 03/30/2009

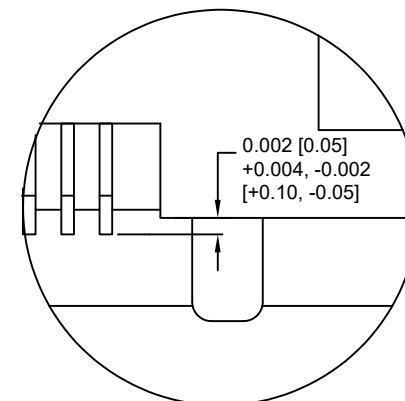
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SCALE: NTS	SHEET 1	OF 2	REV 15
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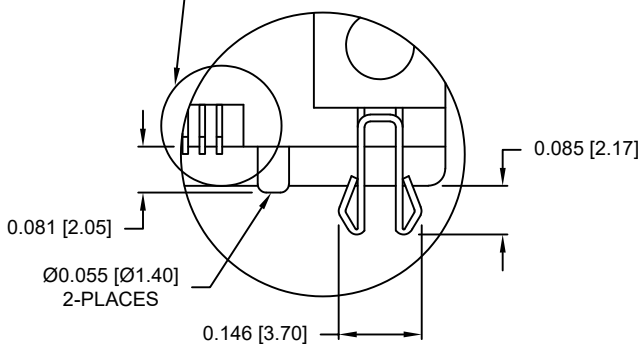
RECOMMENDED PCB LAYOUT

CONTACT ARRANGEMENT
1 6 2 7 3 8 4 9 5

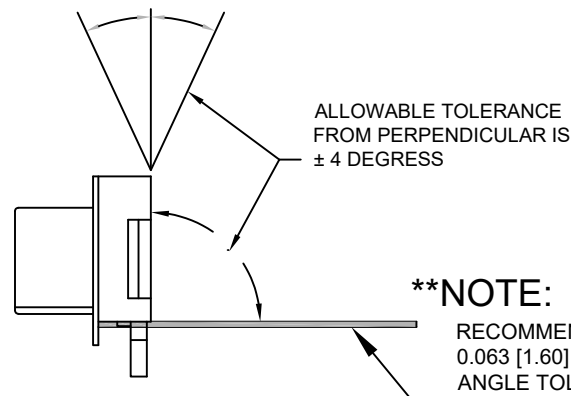


DETAIL "B"
CONTACT COPLANARITY

SEE DETAIL "B"
FOR CONTACT
COPLANARITY



DETAIL "A"



****NOTE:**
RECOMMENDED PCB THICKNESS IS
0.063 [1.60] ± 0.002 [0.05] TO MAINTAIN
ANGLE TOLERANCE

RoHS COMPLIANT

UNITS = inch [mm]

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SHEET OF
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